

FEATURES

■ HIGH POWER

P1dB=44.5dBm at 5.9GHz to 6.4GHz

■ HIGH GAIN

G1dB=10.0dB at 5.9GHz to 6.4GHz

■ BROAD BAND INTERNALLY MATCHED

■ HERMETICALLY SEALED PACKAGE

RF PERFORMANCE SPECIFICATIONS (Ta= 25°C)

CHARACTERISTICS	SYMBOL	CONDITION	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Compression Point	P1dB	VDS= 10V f = 5.9 – 6.4GHz	dBm	43.5	44.5	—
Power Gain at 1dB Compression Point	G1dB		dB	9.0	10.0	—
Drain Current	IDS1		A	—	6.8	7.6
Gain Flatness	ΔG		dB	—	—	±0.6
Power Added Efficiency	ηadd		%	—	37	—
3rd Order Intermodulation Distortion	IM3	Two Tone Test Po=33.5dBm (Single Carrier Level)	dBc	-44	-47	—
Drain Current	IDS2		A	—	6.8	7.6
Channel Temperature Rise	ΔTch	VDS X IDS X Rth(c-c)	°C	—	—	80

ELECTRICAL CHARACTERISTICS (Ta= 25°C)

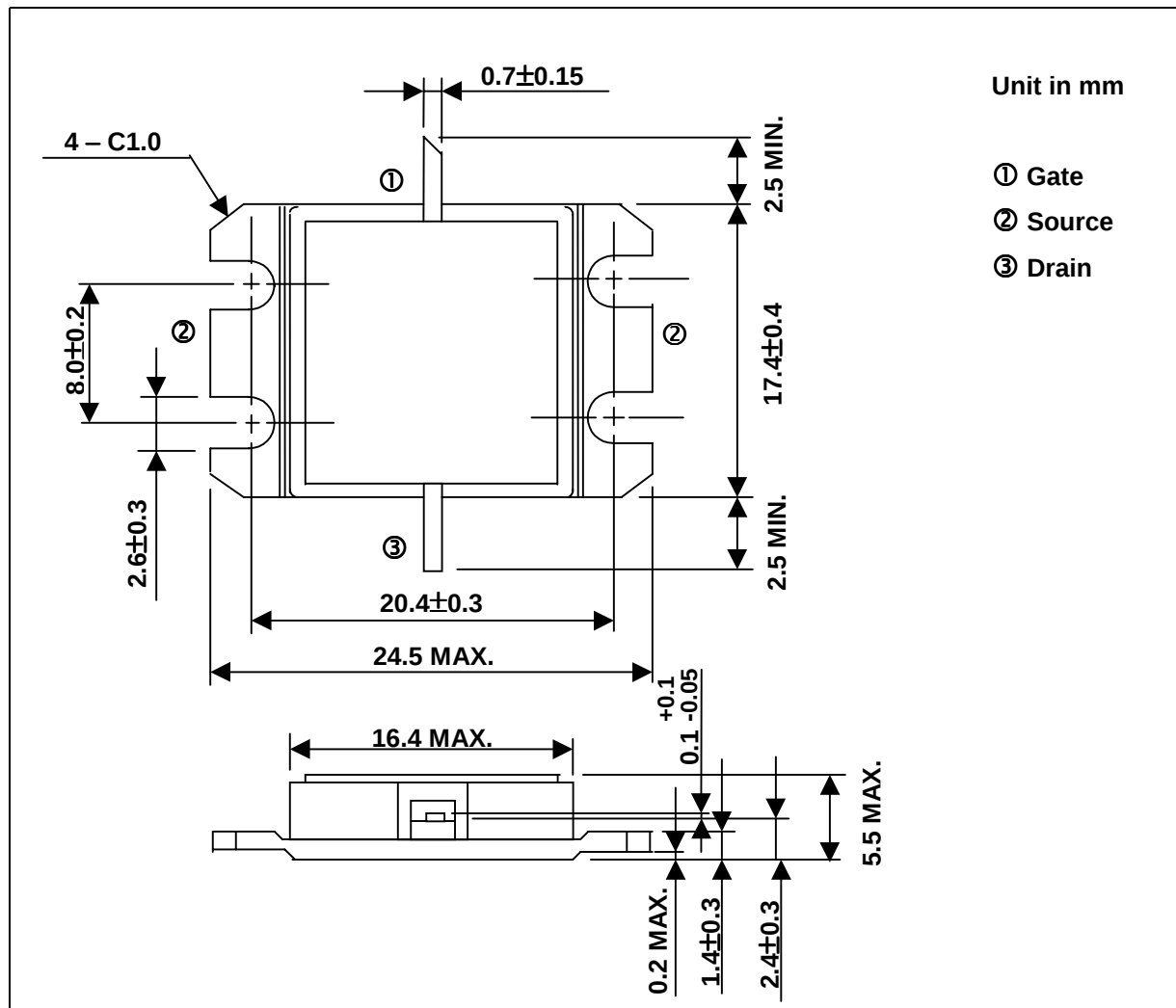
CHARACTERISTICS	SYMBOL	CONDITION	UNIT	MIN.	TYP.	MAX.
Transconductance	gm	VDS= 3V IDS= 8.0A	mS	—	5000	—
Pinch-off Voltage	VGSoff	VDS= 3V IDS= 80mA	V	-1.0	-2.5	-4.0
Saturated Drain Current	IDSS	VDS= 3V VGS= 0V	A	—	14.4	20.0
Gate-Source Breakdown Voltage	VGSO	IGS= -280μA	V	-5	—	—
Thermal Resistance	Rth(c-c)	Channel to Case	°C/W	—	1.2	1.5

◆ The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may results from its use. No license is granted by implication or otherwise under any patent or patent rights of TOSHIBA or others.

The information contained herein is subject to change without prior notice. It is therefor advisable to contact TOSHIBA before proceeding with design of equipment incorporating this product.

ABSOLUTE MAXIMUM RATINGS (Ta= 25°C)

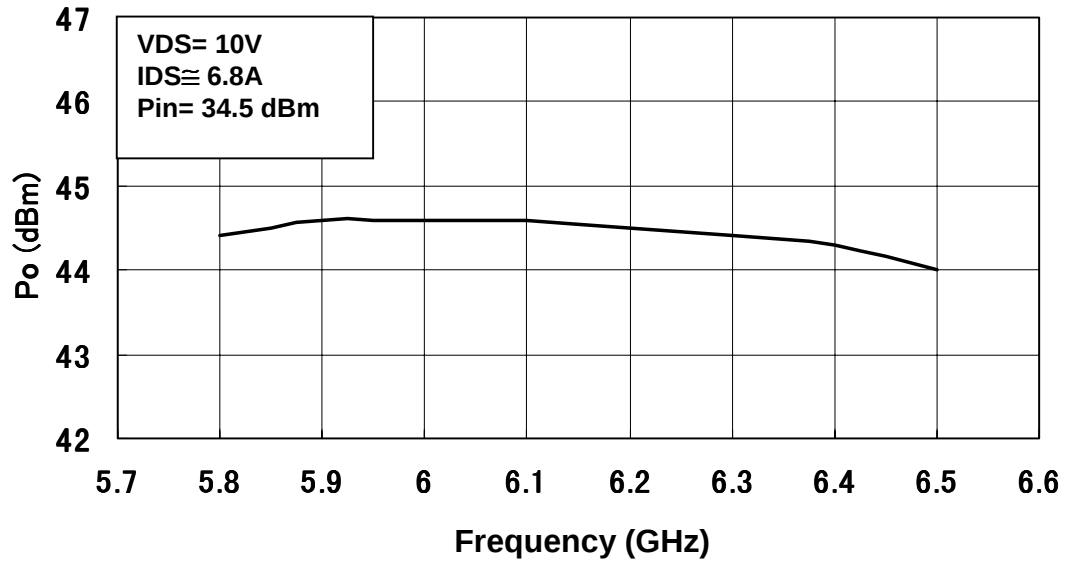
CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain-Source Voltage	VDS	V	15
Gate-Source Voltage	VGS	V	-5
Drain Current	IDS	A	20.0
Total Power Dissipation (Tc= 25 °C)	PT	W	100
Channel Temperature	Tch	°C	175
Storage	Tstg	°C	-65 ~ +175

PACKAGE OUTLINE (2-16G1B)**HANDLING PRECAUTIONS FOR PACKAGED TYPE**

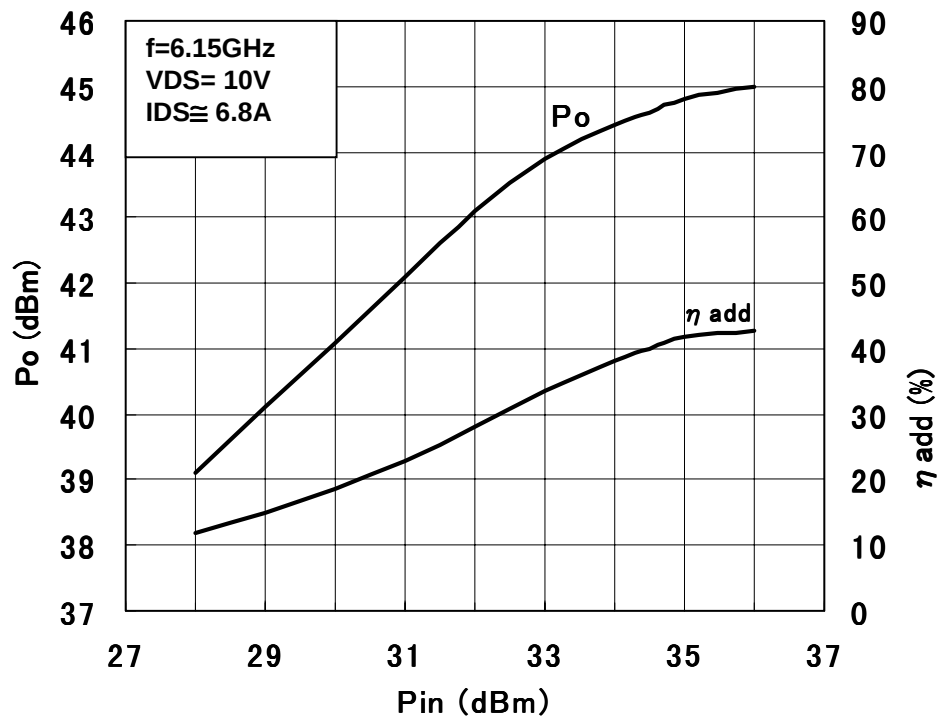
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

RF PERFORMANCES

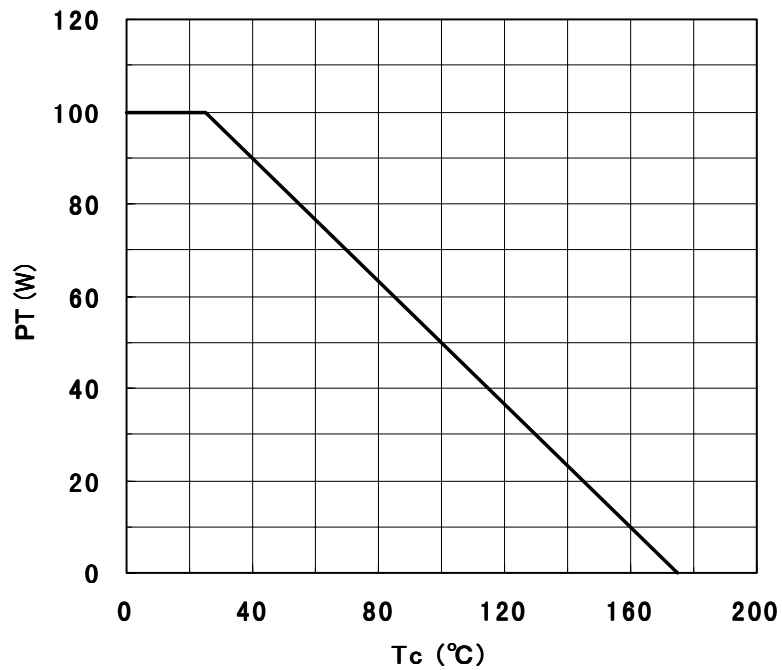
Output Power vs. Frequency



Output Power vs. Input Power



POWER DISSIPATION vs. CASE TEMPERATURE

IM₃ vs. OUTPUT POWER CHARACTERISTICS